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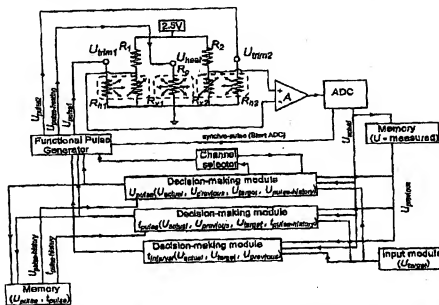
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(54) Title: TRIMMING TEMPERATURE COEFFICIENTS OF ELECTRONIC COMPONENTS AND CIRCUITS



(57) Abstract: There is described methods and circuits for trimming a temperature coefficient of change of a parameter of at least one electrical component while maintaining a substantially constant parameter value, the method comprising applying a heating cycle to trim said parameter value away from a target parameter value and back to said target parameter value, whereby the temperature coefficient of change is modified after applying said heating cycle.

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